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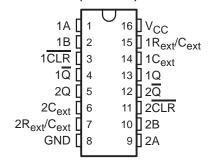
- Dual Versions of Highly Stable SN54121 and SN74121 One Shots
- SN54221 and SN74221 Demonstrate Electrical and Switching Characteristics That Are Virtually Identical to the SN54121 and SN74121 One Shots
- Pinout Is Identical to the SN54123, SN74123, SN54LS123, and SN74LS123
- Overriding Clear Terminates Output Pulse

	MAXIMUM OUTPUT PULSE
TYPE	LENGTH(S)
SN54221	21
SN74221	28
SN54LS221	49
SN74LS221	70

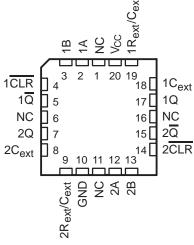
description/ordering information

The '221 and 'LS221 devices are dual multivibrators with performance characteristics virtually identical to those of the '121 devices. Each multivibrator features a negative-transition-triggered input and a positive-transition-triggered input, either of which can be used as an inhibit input.

SN54221, SN54LS221 ... J PACKAGE SN74221 ... N PACKAGE SN74LS221 ... D, DB, N, OR NS PACKAGE (TOP VIEW)



SN54LS221 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKAGI	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DDID N	SN74221N		SN74221N
	PDIP – N	Tube	SN74LS221N	SN74LS221N
0°C to 70°C	0010 D	Tube	SN74LS221D	1.0004
0°C to 70°C	SOIC - D	Tape and reel	SN74LS221DR	LS221
	SOP - NS	Tape and reel	SN74LS221NSR	74LS221
	SSOP - DB	Tape and reel	SN74LS221DBR	LS221
	ODID I	T. I.	SNJ54221J	SNJ54221J
−55°C to 125°C	CDIP – J	Tube	SNJ54LS221J	SNJ54LS221J
	LCCC – FK	Tube	SNJ54LS221FK	SNJ54LS221FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. Schmitt-trigger input circuitry (TTL hysteresis) for B input allows jitter-free triggering from inputs with transition at rates as slow as 1 V/s, providing the circuit with excellent noise immunity, typically of 1.2 V. A high immunity to V_{CC} noise, typically of 1.5 V, also is provided by internal latching circuitry.

Once fired, the outputs are independent of further transitions of the A and B inputs and are a function of the timing components, or the output pulses can be terminated by the overriding clear. Input pulses can be of any duration relative to the output pulse. Output pulse length can be varied from 35 ns to the maximum by choosing appropriate timing components. With $R_{ext} = 2 k\Omega$ and $C_{ext} = 0$, an output pulse typically of 30 ns is achieved that can be used as a dc-triggered reset signal. Output rise and fall times are TTL compatible and independent of pulse length. Typical triggering and clearing sequences are shown as a part of the switching characteristics waveforms.

Pulse-width stability is achieved through internal compensation and is virtually independent of V_{CC} and temperature. In most applications, pulse stability is limited only by the accuracy of external timing components.

Jitter-free operation is maintained over the full temperature and V_{CC} ranges for more than six decades of timing capacitance (10 pF to 10 μ F) and more than one decade of timing resistance (2 k Ω to 30 k Ω for the SN54221, $2 \text{ k}\Omega$ to 40 k Ω for the SN74221, $2 \text{ k}\Omega$ to 70 k Ω for the SN54LS221, and $2 \text{ k}\Omega$ to 100 k Ω for the SN74LS221). Throughout these ranges, pulse width is defined by the relationship: $t_w(out) = C_{ext}R_{ext}$ In $2 \approx 0.7$ $C_{ext}R_{ext}$. In circuits where pulse cutoff is not critical, timing capacitance up to $1000\,\mu F$ and timing resistance as low as $1.4\,k\Omega$ can be used. Also, the range of jitter-free output pulse widths is extended if V_{CC} is held to 5 V and free-air temperature is 25°C. Duty cycles as high as 90% are achieved when using maximum recommended R_T. Higher duty cycles are available if a certain amount of pulse-width jitter is allowed.

The variance in output pulse width from device to device typically is less than ±0.5% for given external timing components. An example of this distribution for the '221 is shown in Figure 3. Variations in output pulse width versus supply voltage and temperature for the '221 are shown in Figures 4 and 5, respectively.

Pin assignments for these devices are identical to those of the SN54123/SN74123 or SN54LS123/SN74LS123 so that the '221 or 'LS221 devices can be substituted for those products in systems not using the retrigger by merely changing the value of Rext and/or Cext; however, the polarity of the capacitor must be changed.

FUNCTION TABLE (each monostable multivibrator)

	INPUTS	OUTPUTS				
CLR	Α	В	Q	Q		
L	Χ	Х	L	Н		
X	Н	X	L	Н		
X	Χ	L	L	Н		
Н	L	\uparrow	лţ	†		
Н	\downarrow	Н	лţ	†		
↑‡	L	Н	лţ	†		

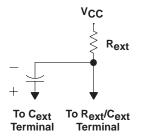
[†] Pulsed-output patterns are tested during AC switching at 25°C with $R_{ext} = 2 k\Omega$, and $C_{ext} = 80 pF.$



[‡]This condition is true only if the output of the latch formed by the two NAND gates has been conditioned to the logic 1 state prior to CLR going high. This latch is conditioned by taking either A high or B low while CLR is inactive (high).

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timing component connections



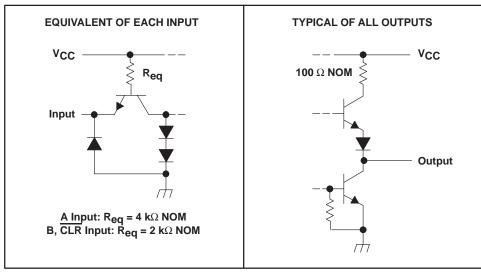
NOTE: Due to the internal circuit, the $R_{\text{ext}}/C_{\text{ext}}$ terminal never is more positive than the C_{ext} terminal.

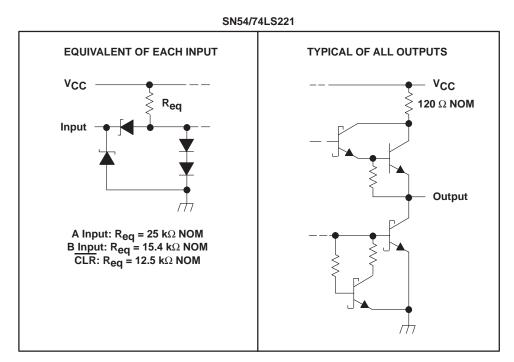


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schematics of inputs and outputs

SN54/74221





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		7 V
Input voltage range, V _I (see Note 1): 'LS221		7 V
· · · · · · · · · · · · · · · · · · ·		
Package thermal impedance, θ _{JA} (see Note 2)): D package	73°C/W
, , ,	DB package	
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, Teta	, ,	

recommended operating conditions (see Note 3)

					SN54221			SN74221			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V		
ЮН	High-level output current				-800			-800	μΑ		
loL	Low-level output current				16			16	mA		
	B: (() ()	B input	1*			1			V/s		
Δv/Δt	Rise or fall of input pulse rate	A input	1*			1			V/μs		
TA	Operating free-air temperature		-55		125	0		70	°C		

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	24244555		NIDITIONS.	,	SN54221		,	SN74221		
	PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
V _{T+}	Positive-going threshold voltage, B input	V _{CC} = MIN			1.55	2*		1.55	2	V
V _T -	Negative-going threshold voltage, B input	V _{CC} = MIN		0.8*	1.35		0.8	1.35		V
VIK		V _{CC} = MIN,	I _I = -12 mA			-1.5			-1.5	V
Vон		$V_{CC} = MIN,$	I _{OH} = -800 μA	2.4	3.4		2.4	3.4		V
VOL		$V_{CC} = MIN,$	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
П		$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
1	A input	.,	V 04V			40			40	•
¹IH	CLR, B input	$V_{CC} = MAX,$	V _I = 2.4 V			80			80	μΑ
Ι.	A input	V MAY	V 04V			-1.6			-1.6	4
IIL	CLR, B input	$V_{CC} = MAX,$	$V_I = 0.4 V$			-3.2			-3.2	mA
los§		$V_{CC} = MAX$		-20		-55	-18		-55	mA
laa	Quiescent	Vaa MAX			26	50*		26	50	A
Icc	Triggered	VCC = MAX			46	80*		46	80	mA

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

			SN54	1221	SN74	UNIT	
		MIN	MAX	MIN	MAX	UNII	
t _W Pulse duration		A or B input	50		50		
		CLR	20		20		ns
t _{su}	Setup time, inactive-state¶	CLR	15		15		ns
R _{ext}	External timing resistance		1.4*	30*	1.4	40	kΩ
C _{ext}	External timing capacitance		0*	1000*	0	1000	μF
	Output duty cycle	$R_{ext} = 2 k\Omega$		67%	·	67%	
	Output duty cycle	R _{ext} = MAX R _{ext}		90%		90%	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

 $[\]P$ Inactive-state setup time also is referred to as recovery time.

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switching characteristics V_{CC} = 5 V, R_L = 400 Ω , T_A = 25°C (see Figures 1 and 2)

DADAMETED	FROM	то	TEST CO.	NDITIONS	S	N54221		S	N74221		LINUT			
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT			
	А	_				45	70		45	70				
^t PLH	В	Q	0 00 - 5	D 01-0		35	55		35	55				
,	А	ĪQ	$C_{\text{ext}} = 80 \text{ pF},$	$R_{\text{ext}} = 2 \text{ K}\Omega$		50	80		50	80	ns			
^t PHL	В	Q				40	65		40	65				
t _{PHL}	CLR	Q	0 00 - 5	D 010			27			27				
t _{PLH}	CLR	la	$C_{ext} = 80 pF,$	Cext = 60 pr,	Cext = 60 pr,	Cext = 60 pr,	$R_{\text{ext}} = 2 \text{ K}\Omega$			40			40	ns
			$C_{ext} = 80 pF,$	$R_{ext} = 2 k\Omega$	70	110	150	70	110	150				
	A == D	Q or Q	$C_{ext} = 0$,	$R_{ext} = 2 k\Omega$	17	30	50	17	30	50	ns			
t _W	A or B	Q or Q	$C_{ext} = 100 \text{ pF}, R_{ext} = 10 \text{ k}\Omega$	650	700	750	650	700	750					
			$C_{ext} = 1 \mu F$,	$R_{ext} = 10 \text{ k}\Omega$	6.5*	7	7.5*	6.5	7	7.5	ms			

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

recommended operating conditions (see Note 4)

			SN54LS221			SI			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
loн	High-level output current				-400			-400	μΑ
loL	Low-level output current				4			8	mA
	Di CH Ci e le	B input	1*			1			V/s
Δv/Δt	Rise or fall of input pulse rate	A input	1*			1			V/µs
TA	Operating free-air temperature		-55		125	0		70	°C

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	24244555		NIDITIONS.	SI	N54LS22	:1	SI	N74LS22	1	
	PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
V _{T+}	Positive-going threshold voltage, B input	V _{CC} = MIN			1	2*		1	2	٧
V _T –	Negative-going threshold voltage, B input	V _{CC} = MIN		0.7*	0.9		0.8	0.9		٧
VIK	-	V _{CC} = MIN,	I _I = -18 mA			-1.5			-1.5	V
Vон		$V_{CC} = MIN,$	I _{OH} = -400 μA	2.5	3.4		2.7	3.4		V
.,		\/ A41\1	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	٧
VOL		$V_{CC} = MIN$	I _{OL} = 8 mA					0.35	0.5	V
Ц		$V_{CC} = MAX,$	V _I = 7 V			0.1			0.1	mA
lін		$V_{CC} = MAX$,	V _I = 2.7 V			20			20	μΑ
	A input	., .,,,				-0.4			-0.4	
IIL	CLR, B input	$V_{CC} = MAX$,	$V_{I} = 0.4 V$			-0.8			-0.8	mA
los§		VCC = MAX		-20		-100	-20		-100	mA
laa	Quiescent	Vaa – MAY			4.7	11		4.7	11	m A
Icc	Triggered	VCC = MAX			19	27*		19	27	mA

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

			SN54I	S221	SN74L	S221	
		MIN	MAX	MIN	MAX	UNIT	
t _W Pulse duration		A or B	50		50		
		CLR	40		40		ns
t _{su}	Setup time, inactive state¶	CLR	15		15		ns
R _{ext}	External timing resistance		1.4*	70*	1.4	100	kΩ
C _{ext}	External timing capacitance		0*	1000*	0	1000	μF
	Output duty cycle	$R_T = 2 k\Omega$		50%		50%	
	Output duty cycle	R _T = MAX R _{ext}		90%		90%	

 $[\]underline{\ast}$ On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

 $[\]P$ Inactive-state setup time also is referred to as recovery time.

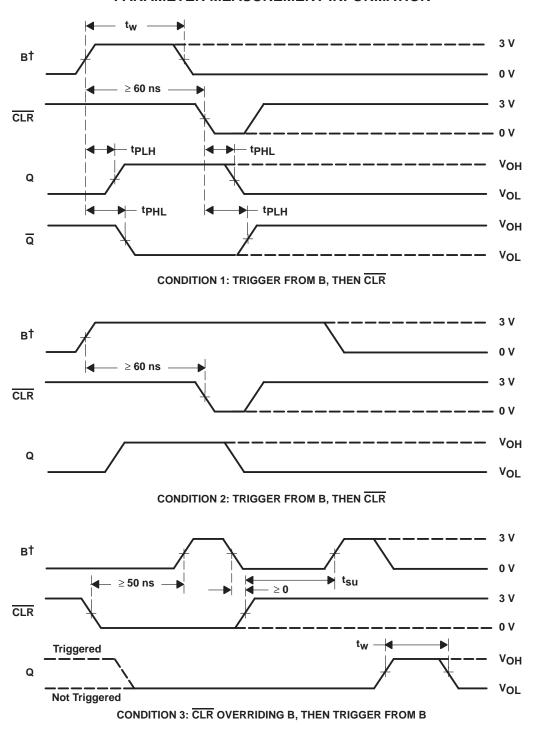
SN54221, SN54LS221, SN74221, SN74LS221 DUAL MONOSTABLE MULTIVIBRATORS WITH SCHMITT-TRIGGER INPUTS SDLS213B - DECEMBER 1983 - REVISED NOVEMBER 2004

switching characteristics V_{CC} = 5 V, R_L = 2 kΩ, T_A = 25 $^{\circ}C$ (see Figures 1 and 2)

BARAMETER	FROM	то	TEOT 00	NDITIONS	SN	154LS22	:1	SN	74LS22	1						
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT					
_	Α	_				45	70		45	70						
^t PLH	В	Q	0 00	D 010		35	55		35	55						
	Α	Q	$C_{\text{ext}} = 80 \text{ pF}, R_{\text{ext}} = 2 \text{ k}\Omega$	$C_{\text{ext}} = 60 \text{ pr},$	C _{ext} = 60 pr,	Cext = 60 pr,	C _{ext} = 60 pr,	Cext = 60 pr,	$R_{\text{ext}} = 2 \text{ K}\Omega$		50	80		50	80	ns
^t PHL	В	Q			40	65		40	65							
tPHL	OL D	Q	0 00 - 5	D 010		35	55		35	55						
t _{PLH}	CLR	la	$C_{ext} = 80 pF,$	$R_{\text{ext}} = 2 \text{ K}\Omega$		44	65		44	65	ns					
			$C_{ext} = 80 pF,$	$R_{ext} = 2 k\Omega$	70	120	150	70	120	150						
	A = = D	Q or Q	$C_{\text{ext}} = 0$, $R_{\text{ext}} = 2 \text{ k}\Omega$ $C_{\text{ext}} = 100 \text{ pF}$, $R_{\text{ext}} = 10 \text{ k}\Omega$	$R_{ext} = 2 k\Omega$	20	47	70	20	47	70	ns					
t _W	A or B	Q or Q		670	740	810	670	740	810							
			$C_{ext} = 1 \mu F$,	$R_{ext} = 10 \text{ k}\Omega$	6*	6.9	7.5*	6	6.9	7.5	ms					

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

PARAMETER MEASUREMENT INFORMATION



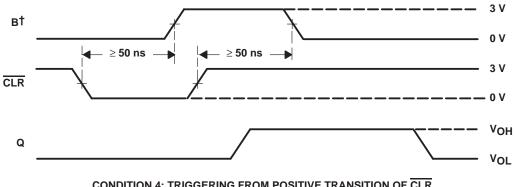
† A is low.

Figure 1. Switching Characteristics

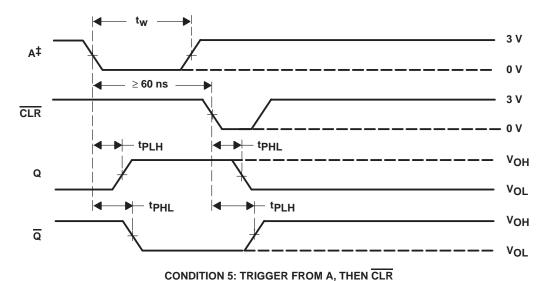


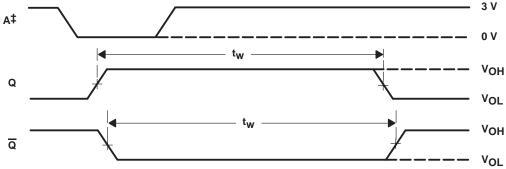
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PARAMETER MEASUREMENT INFORMATION



CONDITION 4: TRIGGERING FROM POSITIVE TRANSITION OF CLR





CONDITION 6: TRIGGER FROM A

† A is low.

‡B and CLR are high.

NOTES: A. Input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50\Omega$; for SN54/74221, $t_\Gamma \leq$ 7 ns, $t_f \le 7$ ns, for SN54/74LS221, $t_r \le 15$ ns, $t_f \le 6$ ns.

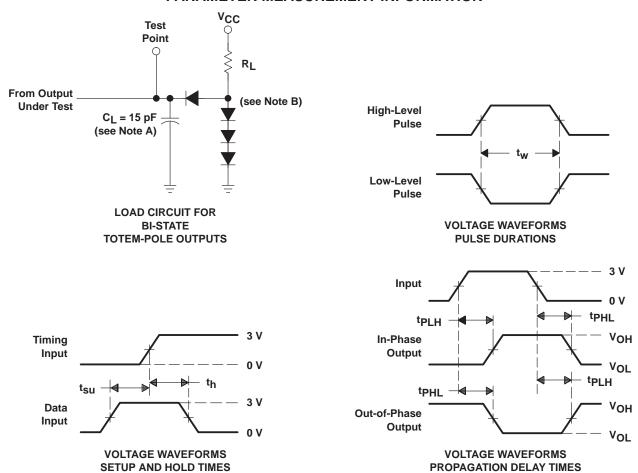
B. All measurements are made between the 1.5-V points of the indicated transitions for the SN54/74221 or between the 1.3-V points for the SN54/74LS221.

Figure 1. Switching Characteristics (Continued)



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

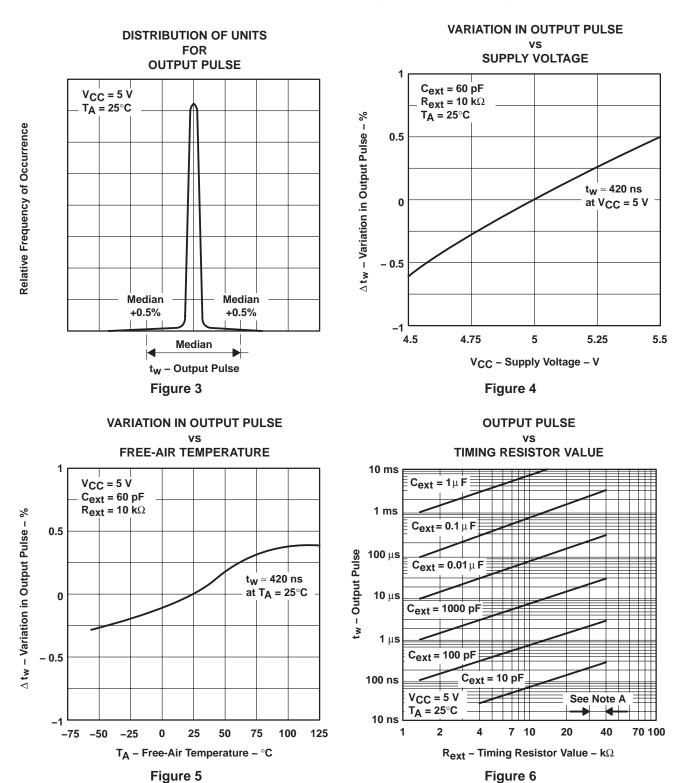
- B. All diodes are 1N3064 or equivalent.
- C. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
- D. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$ and, for SN54/74221, $t_f \leq 7$ ns, $t_f \leq 7$ ns, for SN54/74LS221, $t_f \leq 15$ ns, $t_f \leq 6$ ns.
- E. All measurements are made between the 1.5-V points of the indicated transitions for the SN54/74221 or between the 1.3-V points for the SN54/74LS221.

Figure 2. Load Circuits and Voltage Waveforms



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TYPICAL CHARACTERISTICS (SN54/74221 ONLY)†



† Data for temperatures below 0°C and above 70°C, and for supply voltages below 4.75 V and above 5.25 V are applicable for the SN54221 only. NOTE A: These values of resistance exceed the maximum recommended for use over the full military temperature range of the SN54221.







25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Sample
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
5962-8771101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8771101EA SNJ54221J	Sample
76042012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76042012A SNJ54LS 221FK	Sample
7604201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604201EA SNJ54LS221J	Sample
7604201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604201FA SNJ54LS221W	Sample
JM38510/31402B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31402B2A	Sample
JM38510/31402BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31402BEA	Sample
JM38510/31402BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31402BFA	Sample
M38510/31402B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31402B2A	Sample
M38510/31402BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31402BEA	Sample
M38510/31402BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31402BFA	Sample
SN54221J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54221J	Sample
SN54LS221J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS221J	Sample
SN74221N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74221N	Sample
SN74221NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74221N	Sample
SN74LS221D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sampl





25-Sep-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS221DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Samples
SN74LS221DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS221	Sample
SN74LS221N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS221N	Sample
SN74LS221N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS221NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS221N	Sample
SN74LS221NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS221	Sample
SN74LS221NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS221	Sample
SN74LS221NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS221	Sample
SNJ54221J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8771101EA SNJ54221J	Sample
SNJ54LS221FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type -55 to 125		76042012A SNJ54LS 221FK	Sample
SNJ54LS221J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604201EA SNJ54LS221J	Sample
SNJ54LS221W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7604201FA SNJ54LS221W	Sample

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PACKAGE OPTION ADDENDUM



25-Sep-2013

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54221, SN54LS221, SN74221, SN74LS221:

- Catalog: SN74221, SN74LS221
- Military: SN54221, SN54LS221

NOTE: Qualified Version Definitions:

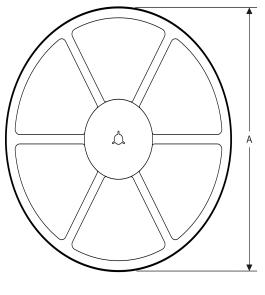
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

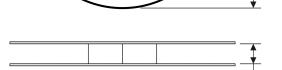
PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

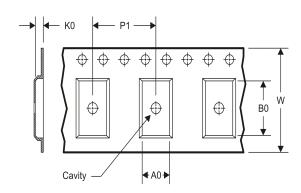
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



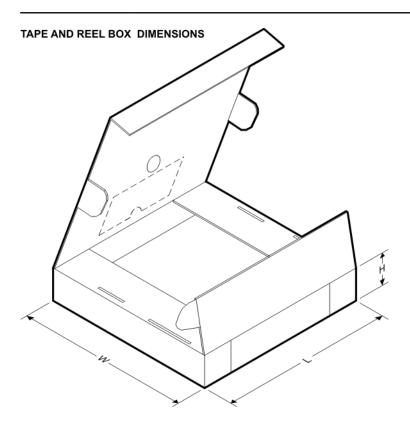
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS221DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS221DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS221NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74LS221DBR	SSOP	DB	16	2000	367.0	367.0	38.0	
SN74LS221DR	SOIC	D	16	2500	333.2	345.9	28.6	
SN74LS221NSR	SO	NS	16	2000	367.0	367.0	38.0	

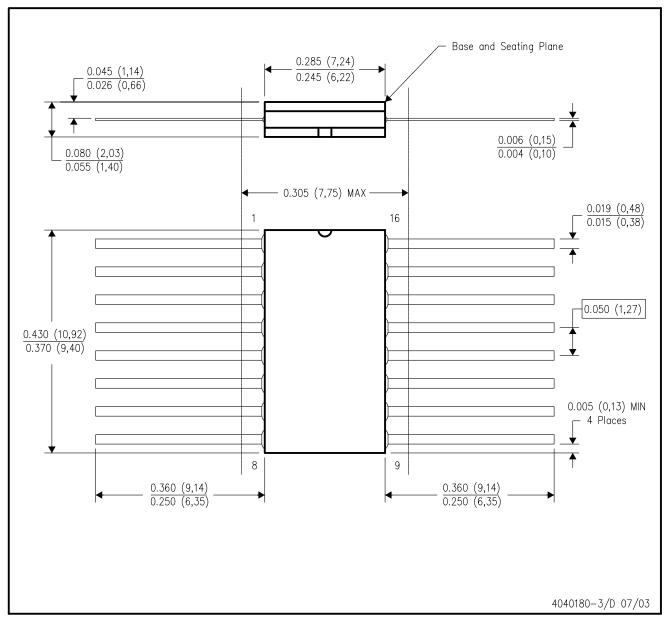
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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